



naturally adaptive.



SMART-SIZED MODULAR PICK-AND-PLACE

Introducing - The Fox Technology - for all types of components and devices. Expandable in any direction.



CELL SOLUTION

combined process.

Placing & dispensing in single pass-through
Jet dispensing of solder paste, glue & more

productivity.

Up to 7'000 – 18'800 cph per module
 Up to 150'000 dots/h (with Piezo Jet Valve)

small footprint.

Up to 200 feeder lanes on 1 m² + trays
Up to 420 feeder lanes per line (3 modules)

mineral cast

No vibration, symmetrical mineral castingNo warpage, no thermal drift

quick changeover.

Nonstop production, intelligent smart feederNonstop feeder and production changeover

linear motors

Fast, reliable double drive linear motors
No maintenance, longest lifetime

naturally adaptive.



solder paste jet printing

Dynamic Shockwave Technology. Adaptable for different jettable pastes (T4-7). Adaptable for special applications (nozzle, tappet, temperature etc.). Optional needles for deep cavities.

A WORLD OF BENEFITS FROM NPI TO HIGH FLEX, HIGH SPEED PRODUCTION



Configurable heads with 1-4 placement-axis. 2,5D and 3D dispensing and jetting, High resolution digital vision system with auto component teach-in and irregular ball recognition.



Full operator support - Automated error analysis & KPI. Training, support and troubleshooting via advanced remote access. Investment protection; all options and heads retrofittable.



Multi flexible feeder, multi lane cassette or highly accurate single lane feeder. Tape, Stick, Strip, Tray slider. Largest component spectrum; 008004 up to 80 x 80 mm, component height up to 25 mm.



MULTITALENT SOFTWARE AT YOUR FINGERTIPS State of the art, full graphics, 21.5" 16:9 touch screen, Windows – 64 bit, fingertip operation, universal CAD conversion, zoom at camera windows, all-in-one job planning, setup optimisation, stock management, ERP/MES connection, data analysis, line management, traceability down to single component and more

optional

Laser Height Measurement Compensation of PCB warpage Dispensing and Jetting Vacuum cleaning station for nozzles and tips Tray Slider Unique system to increase the amount of trays Increase Boardsize Table extension to increase the processable board size Additional: Electrical component test system, vision box to increase component size to be placed, clean room cover and more





naturally adaptive.

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Productivity	Optimum placement speed	7'000 cph (1-axis)	12'000 cph (2-axes)	18'800 cph (4-axes)
	Optimum jetting speed	-	150'000 dots/h	-
Feeder	Feeder capacity 8 mm tape	180 (120 inline)	180 (120 inline)	200 (140 inline)
Components	Component size range	008004 (imp.) up to 80 x 80 mm (Note specs for constraints)		
Accuracy	Placement accuracy (x, y)	Chip ± 40 μm (3σ) / QFP ± 30 μm (3σ)		
PCB	Max. PCB dimensions	406 x 305 mm (16 x 12")		
Dimensions	Machine footprint	880 x 1090 mm (34.7 x 43")		

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A NANODIMENSION DIVISION

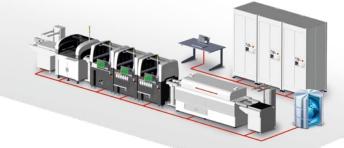
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OUR FOCUS - YOUR SOLUTION SMART SMT EQUIPMENT

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